

APPARATUS FOR POLISHING AND METHOD OF POLISHING

ABSTRACT

There is provided an apparatus for polishing, comprising a polishing table configured to support and rotate a polishing pad; a holder configured to hold an object and press the object against the polishing pad; a polishing solution supply device provided with a contact member and configured to supply a polishing solution to an opening in a bottom face of the contact member in a state that the contact member comes into contact with or is adjacent to the polishing pad, thereby spreading the polishing solution on the polishing pad, the polishing solution supply device causing at least part of used polishing solution returned by rotation of the polishing pad to be dammed up by the contact member and setting the contact member either in a direction of keeping the dammed up polishing solution on the polishing pad or in a direction of discharging the dammed up polishing solution, according to an angle of the polishing solution supply device with respect to a radial direction of the polishing pad; an arm linked with the polishing solution supply device; a rotating mechanism configured to rotate the polishing solution supply device with respect to the arm; and a controller configured to control the rotating mechanism to change the angle of the polishing solution supply device with respect to the radial direction of the polishing pad and thereby control a discharge amount of the polishing solution by the contact member of the polishing solution supply device.

Representative drawing: Fig. 10A